



Material Content Data Sheet



Sales Product Name		TDA21240		Issued		19. January 2018		
MA#		MA001650100						
Package		PG-IQFN-30-2		Weight*		55.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.160	2.10	2.10	21015	21015
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		83	
	non noble metal	zinc	7440-66-6	0.018	0.03		334	
	non noble metal	iron	7439-89-6	0.368	0.67		6673	
wire	non noble metal	copper	7440-50-8	14.956	27.10	27.81	270967	278057
	non noble metal	copper	7440-50-8	0.085	0.15	0.15	1533	1533
	encapsulation	organic material	carbon black	1333-86-4	0.047	0.08		848
	plastics	epoxy resin	-	2.411	4.37		43676	
	inorganic material	silicondioxide	60676-86-0	20.948	37.98	42.43	379512	424036
leadfinish	non noble metal	tin	7440-31-5	0.593	1.07	1.07	10739	10739
plating	noble metal	silver	7440-22-4	0.040	0.07	0.07	728	728
glue	plastics	epoxy resin	-	0.079	0.14		1433	
	noble metal	silver	7440-22-4	0.237	0.43	0.57	4298	5731
solder	noble metal	silver	7440-22-4	0.008	0.01		147	
	non noble metal	tin	7440-31-5	0.016	0.03		293	
	non noble metal	lead	7439-92-1	0.299	0.54	0.58	5424	5864
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		14	
	non noble metal	zinc	7440-66-6	0.003	0.01		56	
	non noble metal	iron	7439-89-6	0.062	0.11		1116	
	non noble metal	copper	7440-50-8	2.502	4.53	4.65	45328	46514
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.003	0.01		62	
	non noble metal	zinc	7440-66-6	0.014	0.02		247	
	non noble metal	iron	7439-89-6	0.273	0.49		4939	
	non noble metal	copper	7440-50-8	11.069	20.05	20.57	200535	205783
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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